


APPLICATION DATA SHEET

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Title of Invention	WIRING SUBSTRATE AND ELECTRONIC PARTS PACKAGING STRUCTURE		
Application Type : regular, utility Attorney Docket Number : 040169			
Correspondence address: Customer Number: 23850 			
Priority Data: Doc.No: 2003-120499; Country -JP ; Date: 2003-04-24 us-priority-claimed			
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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